



TECHNICAL DATA SHEET

KEIM MYCAL[®]-LAVA

1. PRODUCT DESCRIPTION

Indoor climate board made of the natural product Perlite, approved by the building authorities according to ETA-12/0573 (25, 30 mm)
ETA-15/0004 (≥ 50 mm).

2. FIELD OF APPLICATION

Plaster base board for a vapour-diffusion-open and heat-insulating structure on the room side of non-insulated exterior walls in the Mycal[®] system; ideal for preventing surface condensation and mould growth due to the powerful combination of moisture-regulating and heat-insulating properties.

Can be applied to: interior walls; ceiling surfaces, indoors; window and door reveals. The function of the system can be proven by suitable simulation methods.

Suitable for: Masonry or concrete, rendered and unrendered; mineral substrates; natural stone; timber frame .

Not suitable for: gypsum renders; wood substrates; metallic substrates; organic substrates; substrates with salt efflorescences.

3. PRODUCT PROPERTIES

- with very good thermic values
- easy to use
- in a handy format
- fibre-free
- fire behaviour: non-flammable, class A1 according to EN 13501-1
- mineral
- alkaline
- harmless to health
- resistant to aging
- Externally monitored by the MPA Nordrhein-Westfalen

MATERIAL CHARACTERISTICS:

- | | |
|-----------------------------------|--------------------------------------|
| - Panel size: | 625 x 416 mm |
| - Panel thickness: | 25, 30, 50, 60 und 80 mm |
| - Edge formation: | square |
| - Water absorption coefficient w: | approx. 118,8 kg/(m ² √h) |
| - Colour shade: | natural white |

COMPOSITION:

Expanded perlite, silicon dioxide, native potato starch, colour pigments

4. APPLICATION INSTRUCTIONS

SUBSTRATE PREPARATION:

The substrate must be strong, dry, clean, sound and free from adhesion-reducing residues and must not be too absorbent. The substrate must be suitable for a tension-resistant adhesion. Substrates containing gypsum as well as vapour-tight coatings, wallpapers or similar must be removed. Highly absorbent substrates must be sufficiently prewetted.

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APPLICATION CONDITIONS:

Ambient and substrate temperature during application and drying from $\geq 5\text{ °C}$ to $\leq 30\text{ °C}$. Do not apply in direct sunlight or on sun-heated substrates. Protect surfaces from direct sun, wind and rain during and after application.

APPLICATION:

Cut to size with a fine-toothed saw.

GLUING:

The panels are butted tightly and glued in a bond from bottom to top. Apply the system-specific adhesive mortar to the entire surface of the insulation panels, to the substrate, or to the insulation panels and the substrate using the floating-buttering method. Push the boards into place. At the edges of the building, the insulation panels are glued offset. All connecting joints are made airtight with a joint sealing tape. An edge insulation strip must be inserted at the connection to floors and moisture-sensitive components. System supplements are also possible across systems with Multipor Wedge (insulation wedge), Multipor Reveal (reveal panel), Mycal-CS-Dämmkeil (insulation wedge) or Mycal-CS-Laibungsplatte (reveal panel). General instruction with regard to gluing: Do not apply adhesive to the panel joints. Do not create an insulation panel joint over a joint in the substrate underneath.

DOWELING:

Check the adhesion of the insulation panels after at least 3 days. Insulation panels that are not bonded or damaged must be replaced. In the case of subsequent tiling work, the panels are additionally fastened through the mesh with suitable screw anchors and finished with another layer of KEIM Universalputz.

REINFORCEMENT:

Thickness of the reinforcement layer should be approx. 4 mm. When used as a thin-layer felt and finishing render: Apply the material over the entire surface in a thickness of approx. 3 mm and felt-float or texture.

5. PACKAGING / TECHNICAL DATA

Panel thickness [mm]	Rated value thermal conductivity [W/mK]	Compressive strength [kPa]	m ² per bundle	m ² per pallet
25	0,055*	≥ 300	3.12	56.16
30	0,050*	≥ 200	2.60	46.80
50	0,045*	≥ 200	1.56	28.08
60	0,045*	≥ 200	1.30	23.40
80	0,045*	≥ 200	1.04	18.72

PACKAGING / TECHNICAL DATA ADDITIONAL INFORMATION:

* Nominal value of thermal conductivity λ_D (23/50)

6. STORAGE

Storage conditions
dry protect against weathering

7. DISPOSAL

EC WASTE CODE:

Waste code: 17 06 04

8. SAFETY INSTRUCTIONS

no particular indications

9. CERTIFICATES & QUALITY SEALS



The stated values and properties are the result of extensive development work and practical experience. Our recommendations for application, whether given verbally or in writing, are intended to provide assistance in the selection of our products and do not establish a contractual relationship. In particular, they do not release the purchaser and processor from the obligation to convince themselves of the suitability of our products for the intended application with due care, which is general practice in trade and crafts. The general rules of construction technology must be observed. We reserve the right to make modifications to improve the product or its application. This edition supersedes all earlier editions.